

Title (en)

METHOD FOR PRODUCING VIA-CONNECTIONS IN A SUBSTRATE AND SUBSTRATE EQUIPPED WITH SAME

Title (de)

HERSTELLUNG VON DURCHKONTAKTEN DURCH EIN SUBSTRAT

Title (fr)

PROCEDE DE FABRICATION DE CONNEXIONS TRAVERSANTES DANS UN SUBSTRAT ET SUBSTRAT EQUIPE DE TELLES CONNEXIONS

Publication

EP 1210733 A1 20020605 (FR)

Application

EP 00953255 A 20000718

Priority

- FR 0002065 W 20000718
- FR 9909938 A 19990730

Abstract (en)

[origin: FR2797140A1] The invention concerns a method for producing conductive via-connections in a substrate and substrates equipped with such connections. The method for producing conductive via-connections between the front face (2) and the rear face (3) of a substrate consists in: producing in the substrate (1) on the side of the rear face (3), cavities (5) with predetermined depth and cross-section for defining pads (4) with specific cross-section designed to ensure electrical conduction between the two faces (2, 3) and filling up the cavities (5) with a dielectric material (7). The substrate is equipped with conductive via-connections between its front face (2) and its rear face (3). The conductive connections are provided by the pads (4) defined by the cavities (5) filled with a dielectric material (7). The invention is particularly applicable to substrates used for making microsensors.

IPC 1-7

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IPC 8 full level

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CPC (source: EP US)

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C-Set (source: EP US)

H01L 2924/0002 + **H01L 2224/05552**

Citation (examination)

- EP 0316799 A1 19890524 - NISSAN MOTOR [JP]
- WO 9844319 A1 19981008 - YAMATAKE HONEYWELL CO LTD [JP], et al & US 6353262 B1 20020305 - HONDA NOBUAKI [JP]

Citation (third parties)

Third party :

- US 6353262 B1 20020305 - HONDA NOBUAKI [JP]
- US 6475821 B2 20021105 - HONDA NOBUAKI [JP]
- See also references of WO 0109944A1

Designated contracting state (EPC)

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